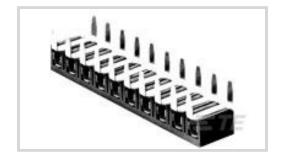
87987-8 - ACTIVE

AMPMODU | AMPMODU MOD 1

TE Internal #: 87987-8 PCB Mount Receptacle, Right Angle, Board-to-Board, 8 Position, 3.96 mm [.156 in] Centerline, Fully Shrouded, Tin, Through Hole -Solder, AMPMODU MOD 1

View on TE.com >





PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Right Angle

Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 1

Features

Product Type Features

Applied Pressure

PCB Connector Assembly Type

Connector System

Standard

PCB Mount Receptacle

Board-to-Board



Header Type	Fully Shrouded						
Connector & Contact Terminates To	Printed Circuit Board						
Configuration Features							
Stackable	No						
PCB Mount Orientation	Right Angle						
Number of Positions	8						
Number of Rows	1						
Board-to-Board Configuration	Perpendicular						
Electrical Characteristics							
Insulation Resistance	5000 MΩ						
Body Features							
Primary Product Color	Black						
Contact Features							
Contact Layout	Inline						
PCB Contact Termination Area Plating Material Thickness	2 μm[79 μin]						

PCB Mount Receptacle, Right Angle, Board-to-Board, 8 Position, 3.96 mm [.156 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, AMPMODU MOD 1



Mating Tab Width	1.58 mm[.062 in]
Mating Tab Thickness	.79 mm[.031 in]
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	2.01 μm[79 μin]
Contact Type	Socket
Contact Current Rating (Max)	5 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.25 mm[.01 in]
Rectangular Termination Post & Tail Width	1.02 mm[.04 in]
Termination Post & Tail Length	2.85 mm[.112 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	3.96 mm[.156 in]
Housing Material	PA66
Dimensions	
Connector Height	7.62 mm[.3 in]
PCB Thickness (Recommended)	1.4 – 2.62 mm[.055 – .103 in]
Usage Conditions	
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Assembly Process Feature	None
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA LR16455, UL E28476
UL Flammability Rating	UL 94V-2

PCB Mount Receptacle, Right Angle, Board-to-Board, 8 Position, 3.96 mm [.156 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, AMPMODU MOD 1



Packaging Features

Packaging Quantity	80							
Packaging Type	Tube							
Product Compliance For compliance documentation, visit the product page on TE.com>								
EU RoHS Directive 2011/65/EU	Compliant							
EU ELV Directive 2000/53/EC	Compliant							
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold							
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022							
	(224) Candidate List Declared Against: JAN 2022							
	(223)							
	SVHC > Threshold:							
	1,6,7,8,9,14,15,16,17,17,18,18-							
	dodecachloropentacyclo							
	[12.2.1.16,9.02,13.05,10]octadeca-7,15-							
	diene (Dechlorane Plus) (17% in							
	Component Part) Article Safe Usage Statements:							

Wash thoroughly after handling. Do not handle until all safety precautions have been read and understood. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content

Solder Process Capability

Not Low Halogen - contains Br or Cl > 900 ppm.

Wave solder capable to 240°C

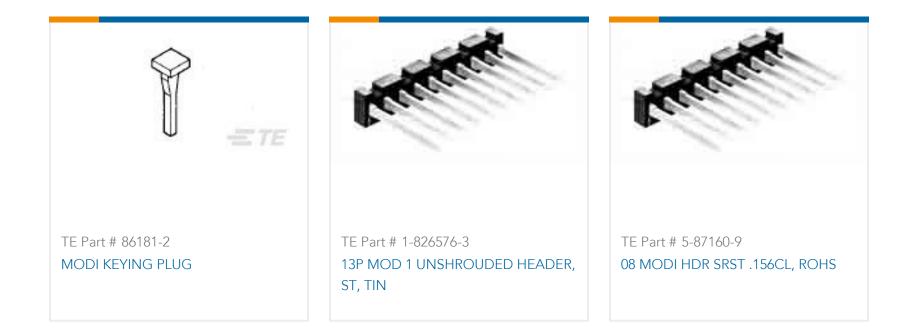
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

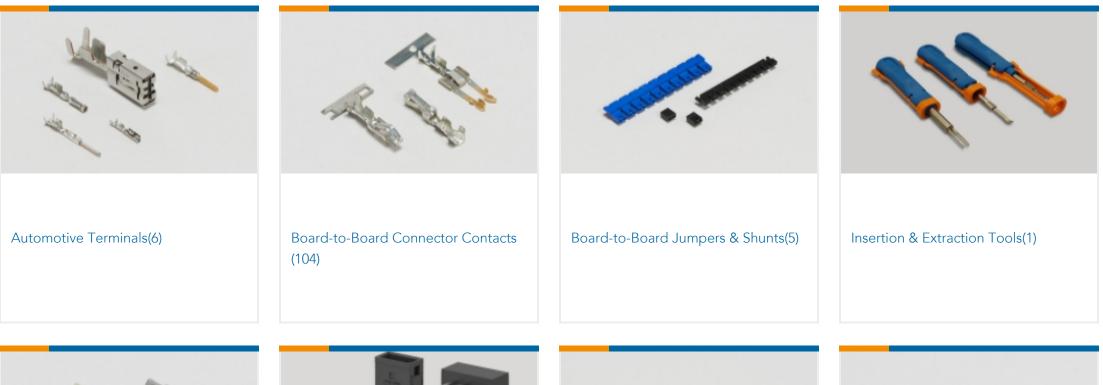
Compatible Parts

PCB Mount Receptacle, Right Angle, Board-to-Board, 8 Position, 3.96 mm [.156 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, AMPMODU MOD 1





Also in the Series | AMPMODU MOD 1











PCB Connector Keying(2)	PCB Headers & Receptacles(372)	Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(2)
		& Housings(44)	

Documents

Product Drawings 08 MODI BDMNT RCPT SR .156CL

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_87987-8_S.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_87987-8_S.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_87987-8_S.3d_stp.zip

English

PCB Mount Receptacle, Right Angle, Board-to-Board, 8 Position, 3.96 mm [.156 in] Centerline, Fully Shrouded, Tin, Through Hole - Solder, AMPMODU MOD 1



By downloading the CAD file I accept and agree to the Terms and Conditions of use

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION_6_7AND8

English

Product Specifications Product Specification

English